



SMD Comm X8G HT150C Flex, Ceramic, 47 pF, 5%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

	Specifications	
1210	Capacitance	47 pF
3.3mm +/-0.4mm	Measurement Condition	1 MHz 1.0Vrms
2.6mm +/-0.3mm	Tolerance	5%
0.78mm +/-0.20mm	Voltage DC	250 VDC
1.5mm MIN	Dielectric Withstanding Voltage	625 VDC
0.6mm +/-0.25mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
	Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
10000	Dissipation Factor	0.1% 1 MHz 1.0Vrms

Aging Rate

Insulation Resistance

Chip Size L W т s в

## **Packaging Specifications** Packaging

Dimensions

Fackaging	TAR, 550mm, Flastic Tape
Packaging Quantity	10000

0% Loss/Decade Hour: Referee

Time is 1000 Hours

100 GOhms